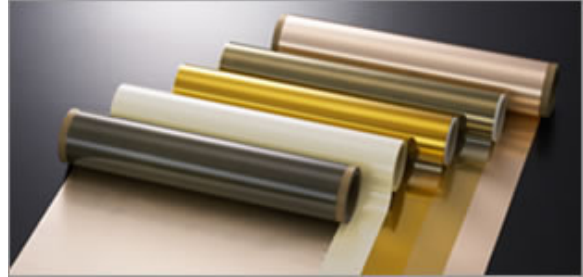


FELIOS FLEX RF775 & RF785 ADHESIVELESS FLEXIBLE LAMINATE

Processing

The FELIOS® Flex line is engineered to perform under a wide array of standard, best industry practices. FELIOS® Flex is totally compatible with standard wet processes including wet through hole plating, desmear, and oxide treatments.



Lamination

Part Temperature: 360-390°F/182-199°C
 Pressure: 200-400 psi/14-28 kg/cm²
 Time: 1-2 hours at temperature

Storage

FELIOS® will retain its original properties for a period of 1 year when stored in its received packaging at humidity below 70%, at temperatures of 40-85°F or 4-29°C. To minimize damage and oxidation, the product should be kept in the original packaging. Felios Flex materials do not need refrigeration.

Handling

All operators handling thin copper clad flexible laminates should use suitable gloves to avoid fingerprints and to minimize cuts. After handling FELIOS® CCL, operators should wash their hands before using the restroom, smoking, eating, or touching any exposed skin.

Drilling Parameters

Standard Rigid PCB drills are not recommended for drilling Polyimide Felios Flex due to the soft nature of materials. Best results are achieved using specially designed carbide drills and endmills with a thin web, large flute-land design, a small margin width and a large helix angle. Please contact our Carbide Drill Product Manager to further assistance with Flex PCB drilling.

	US		Metric	
Drill Size	0.010" – 0.018"	0.020" – 0.055"	0.25 – 0.46 mm	0.5 – 1.4 mm
Surface speed	280 – 460 SFM	500 – 650 SFM	85 – 140 m/min	150 – 200 m/min
Chip Load	0.6 – 1.0 mils/rev	1.0 – 2.5 mils/rev	15 – 25 µ/rev	25 – 65 µ/rev
Hit Count (Max)	1000 - 1500	1500 - 1750	1000 - 1500	1500 - 1750

Contact Us

For more information about the Panasonic FELIOS® Flex Laminates, please contact our Customer or Technical Service Groups at 800-668-5447, or visit our Website www.matrixusa.us.

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